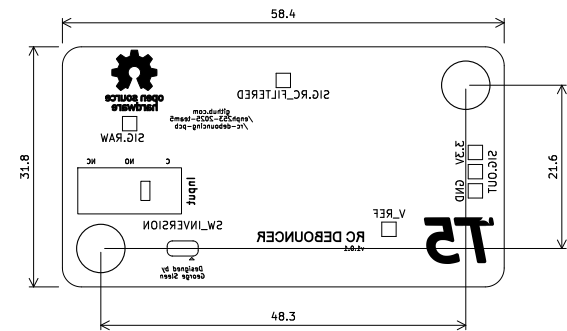


Copper Layer Count:	2	Board Thickness:	1.6000 mm
Board overall dimensions:	58.4200 mm x 31.7500 mm		
Min track/spacing:	0.1000 mm / 0.1000 mm	Min hole diameter:	0.3000 mm
Copper Finish:	None	Impedance Control:	No
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1	core	FR4	1.51 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0



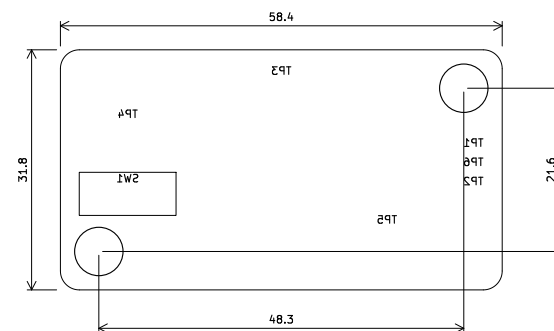
Sheet:
File: rc-debouncer.kicad_pcb

KiCad E.D.A. 9.0.2

Id: 1/4

Copper Layer Count:	2	Board Thickness:	1.6000 mm
Board overall dimensions:	58.4200 mm x 31.7500 mm		
Min track/spacing:	0.1000 mm / 0.1000 mm	Min hole diameter:	0.3000 mm
Copper Finish:	None	Impedance Control:	No
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1	core	FR4	1.51 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0



Sheet:
File: rc-debouncer.kicad_pcb

KiCad E.D.A. 9.0.2

Id: 2/4

BOARD CHARACTERISTICS

Copper Layer Count:2Board Thickness:1.6000 mm

Board overall dimensions:58.4200 mm x 31.7500 mm

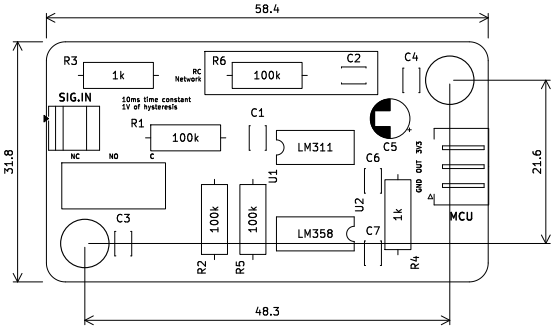
Min track/spacing:0.1000 mm / 0.1000 mmMin hole diameter:0.3000 mm

Copper Finish:NoneImpedance Control:No

Castellated pads:NoPlated Board Edge:No

Edge card connectors:No

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
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F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1	core	FR4	1.51 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0



BOARD CHARACTERISTICS

Copper Layer Count:2Board Thickness:1.6000 mm

Board overall dimensions:58.4200 mm x 31.7500 mm

Min track/spacing:0.1000 mm / 0.1000 mmMin hole diameter:0.3000 mm

Copper Finish:NoneImpedance Control:No

Castellated pads:NoPlated Board Edge:No

Edge card connectors:No

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B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0

